

## NCE N-Channel Enhancement Mode Power MOSFET

### Description

The NCE6020AQ uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### Application

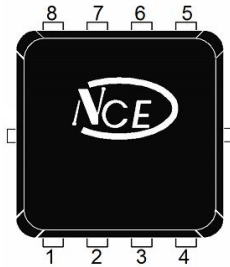
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

### General Features

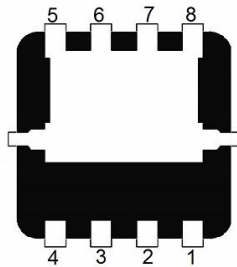
- $V_{DS} = 60V, I_D = 20A$   
 $R_{DS(ON)} < 23m\Omega @ V_{GS}=10V$   
 $R_{DS(ON)} < 30m\Omega @ V_{GS}=4.5V$
- High power and current handling capability
- Fully characterized avalanche voltage and current
- Lead free product is acquired
- Surface mount package

**100% UIS TESTED!**  
**100%  $\Delta V_{ds}$  TESTED!**

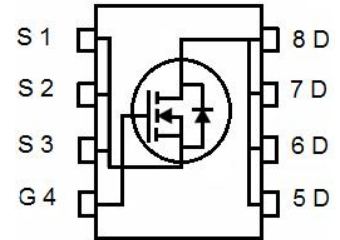
### DFN 3.3X3.3



Top View



Bottom View



Schematic Diagram

### Package Marking and Ordering Information

| Device Marking | Device    | Device Package | Reel Size | Tape width | Quantity |
|----------------|-----------|----------------|-----------|------------|----------|
| NCE6020AQ      | NCE6020AQ | DFN3.3X3.3-8L  | -         | -          | -        |

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

| Parameter   | Symbol             | Limit      | Unit       |
|---|--------------------|------------|------------|
| Drain-Source Voltage                              | $V_{DS}$           | 60         | V          |
| Gate-Source Voltage                               | $V_{GS}$           | $\pm 20$   | V          |
| Drain Current-Continuous                          | $I_D$              | 20         | A          |
| Drain Current-Continuous( $T_C=100^\circ C$ )     | $I_D(100^\circ C)$ | 14         | A          |
| Pulsed Drain Current <sup>(Note 1)</sup>          | $I_{DM}$           | 60         | A          |
| Maximum Power Dissipation                         | $P_D$              | 20         | W          |
| Single pulse avalanche energy <sup>(Note 5)</sup> | $E_{AS}$           | 72         | mJ         |
| Operating Junction and Storage Temperature Range  | $T_J, T_{STG}$     | -55 To 150 | $^\circ C$ |

### Thermal Characteristic

|  |                 |     |              |
|--|-----------------|-----|--------------|
| Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup> | $R_{\theta JC}$ | 6.3 | $^\circ C/W$ |
|--|-----------------|-----|--------------|

## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

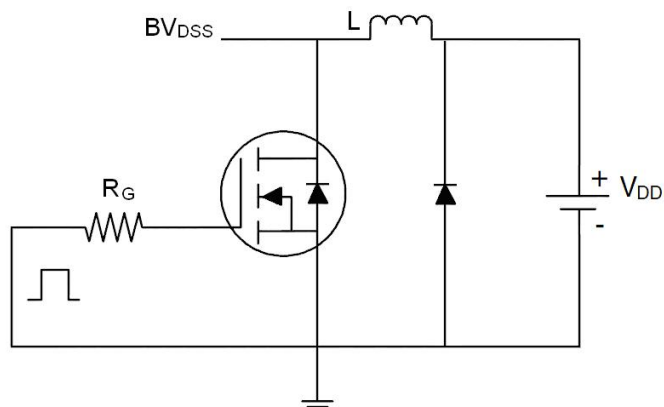
| Parameter                                 | Symbol              | Condition  | Min | Typ   | Max  | Unit |
|---|---------------------|--|-----|-------|------|------|
| <b>Off Characteristics</b>                |                     |  |     |       |      |      |
| Drain-Source Breakdown Voltage            | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA   | 60  | -     | -    | V    |
| Zero Gate Voltage Drain Current           | I <sub>DSS</sub>    | V <sub>DS</sub> =60V, V <sub>GS</sub> =0V  | -   | -     | 1    | μA   |
| Gate-Body Leakage Current                 | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V   | -   | -     | ±100 | nA   |
| <b>On Characteristics</b> (Note 3)        |                     |  |     |       |      |      |
| Gate Threshold Voltage                    | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                             | 1.2 | 1.6   | 2.5  | V    |
| Drain-Source On-State Resistance          | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =10A  | -   | 20    | 23   | mΩ   |
|   |                     | V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A   |     | 25    | 30   |      |
| Forward Transconductance                  | g <sub>FS</sub>     | V <sub>DS</sub> =5V, I <sub>D</sub> =10A   | 11  | -     | -    | S    |
| <b>Dynamic Characteristics</b> (Note 4)   |                     |  |     |       |      |      |
| Input Capacitance                         | C <sub>iss</sub>    | V <sub>DS</sub> =30V, V <sub>GS</sub> =0V,<br>F=1.0MHz                               | -   | 973.2 | -    | PF   |
| Output Capacitance                        | C <sub>oss</sub>    |  | -   | 61.2  | -    | PF   |
| Reverse Transfer Capacitance              | C <sub>rss</sub>    |  | -   | 58.8  | -    | PF   |
| <b>Switching Characteristics</b> (Note 4) |                     |  |     |       |      |      |
| Turn-on Delay Time                        | t <sub>d(on)</sub>  | V <sub>DD</sub> =30V, R <sub>L</sub> =3Ω<br>V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω | -   | 7     | -    | nS   |
| Turn-on Rise Time                         | t <sub>r</sub>      |  | -   | 20    | -    | nS   |
| Turn-Off Delay Time                       | t <sub>d(off)</sub> |  | -   | 16    | -    | nS   |
| Turn-Off Fall Time                        | t <sub>f</sub>      |  | -   | 23    | -    | nS   |
| Total Gate Charge                         | Q <sub>g</sub>      | V <sub>DS</sub> =30V, I <sub>D</sub> =10A,<br>V <sub>GS</sub> =10V                   | -   | 25    |      | nC   |
| Gate-Source Charge                        | Q <sub>gs</sub>     |  | -   | 4.5   |      | nC   |
| Gate-Drain Charge                         | Q <sub>gd</sub>     |  | -   | 6.5   |      | nC   |
| <b>Drain-Source Diode Characteristics</b> |                     |  |     |       |      |      |
| Diode Forward Voltage (Note 3)            | V <sub>SD</sub>     | V <sub>GS</sub> =0V, I <sub>S</sub> =10A   | -   |       | 1.2  | V    |
| Diode Forward Current (Note 2)            | I <sub>S</sub>      |  | -   | -     | 20   | A    |
| Reverse Recovery Time                     | t <sub>rr</sub>     | T <sub>J</sub> = 25°C, I <sub>F</sub> =10A<br>di/dt = 100A/μs (Note 3)               | -   | 29    | -    | nS   |
| Reverse Recovery Charge                   | Q <sub>rr</sub>     |  | -   | 49    | -    | nC   |
| Forward Turn-On Time                      | t <sub>on</sub>     | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)                 |     |       |      |      |

### Notes:

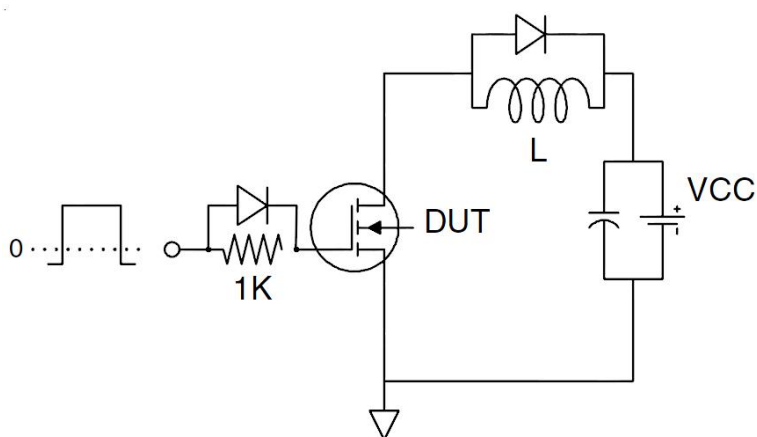
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=30V, V<sub>G</sub>=10V, L=0.5mH, R<sub>G</sub>=25Ω

## Test Circuit

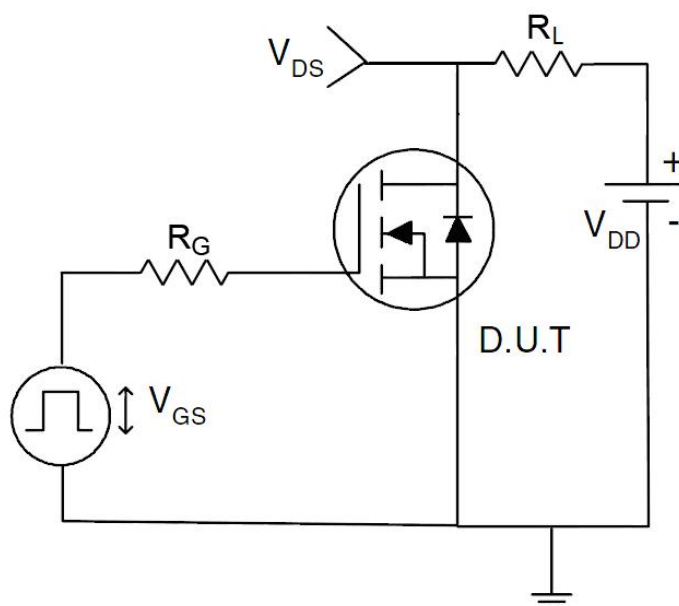
### 1) $E_{AS}$ test Circuit



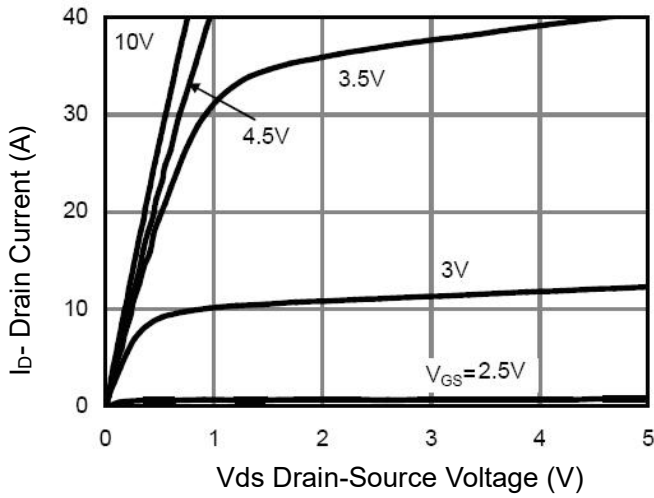
### 2) Gate charge test Circuit



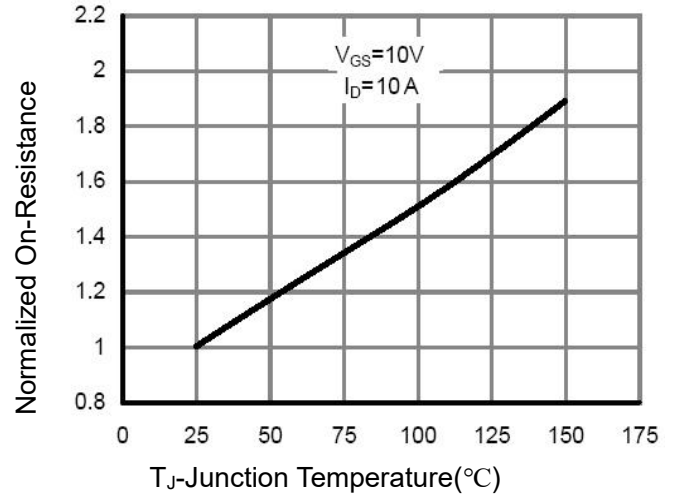
### 3) Switch Time Test Circuit



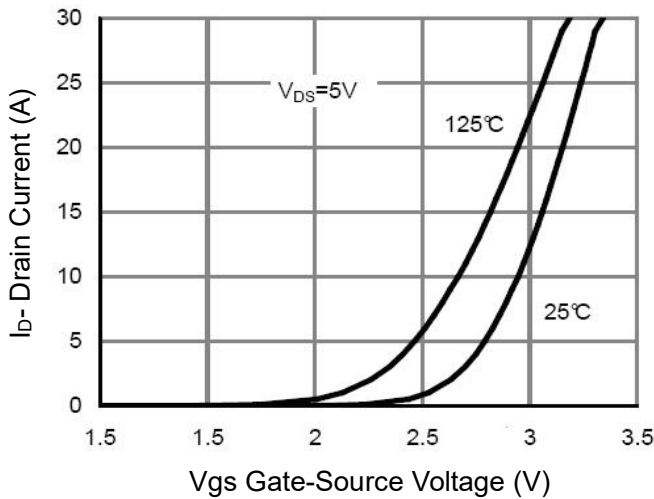
**Typical Electrical and Thermal Characteristics (Curves)**



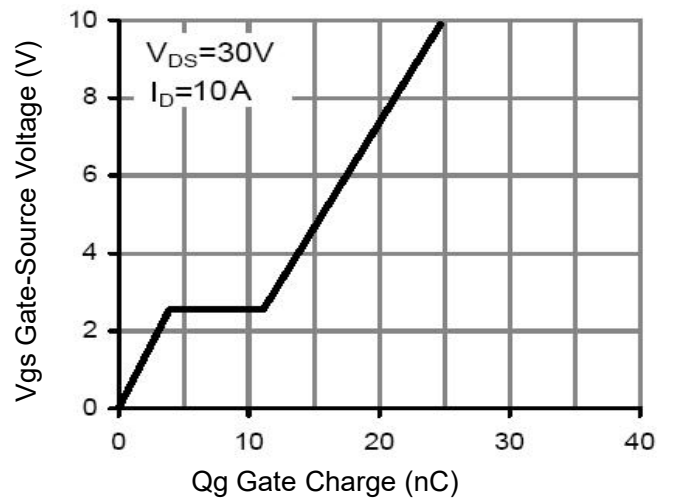
**Figure 1 Output Characteristics**



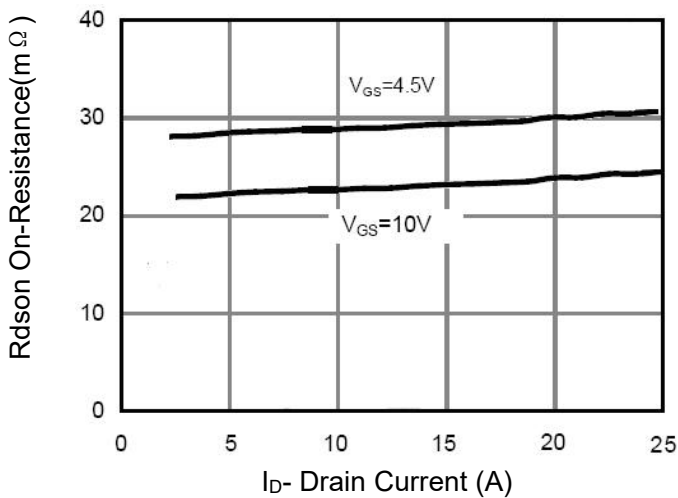
**Figure 4  $R_{ds(on)}$ -Junction Temperature**



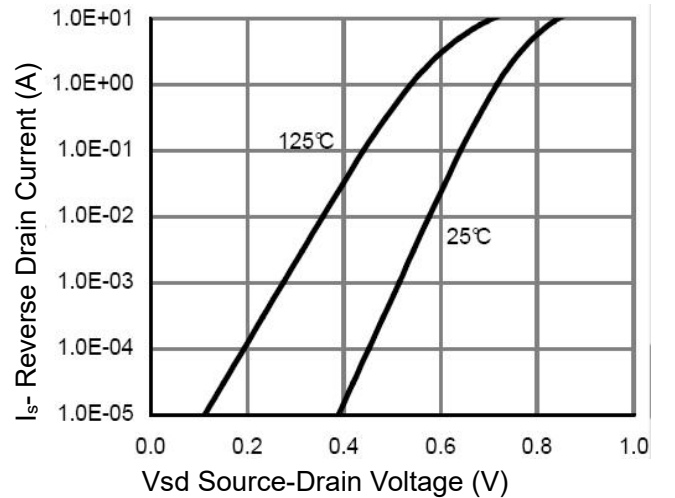
**Figure 2 Transfer Characteristics**



**Figure 5 Gate Charge**



**Figure 3  $R_{ds(on)}$ - Drain Current**



**Figure 6 Source- Drain Diode Forward**

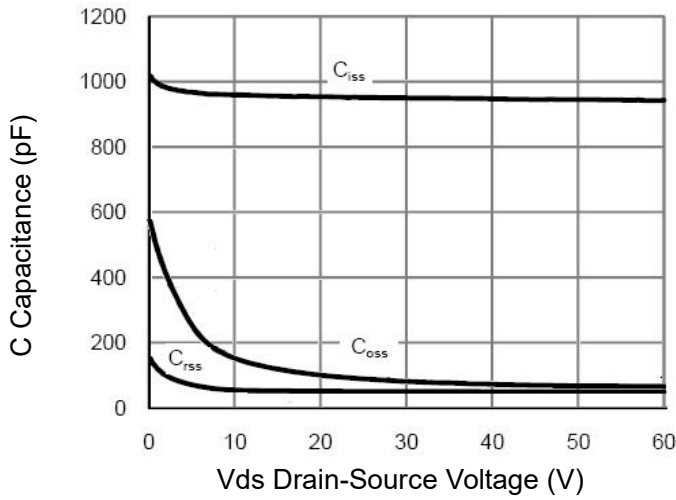


Figure 7 Capacitance vs Vds

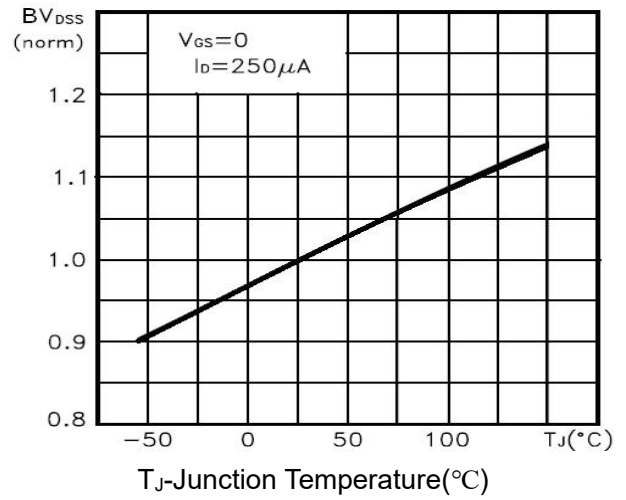


Figure 9  $BV_{DSS}$  vs Junction Temperature

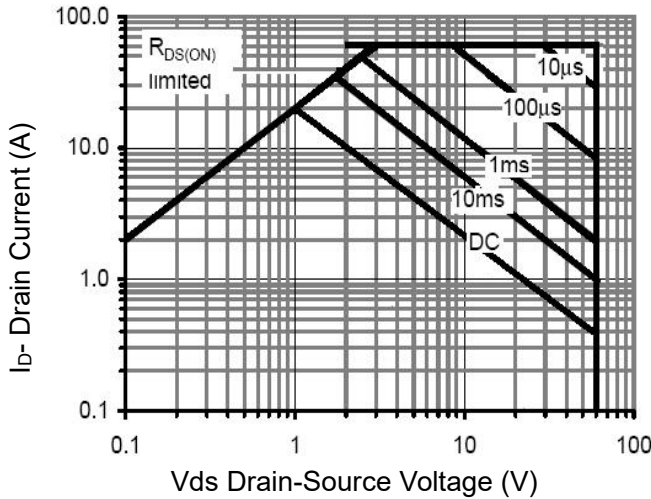


Figure 8 Safe Operation Area

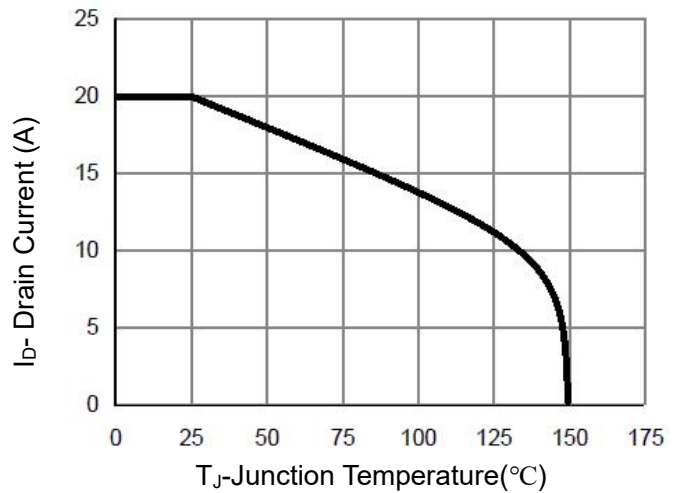


Figure 10 Current De-rating

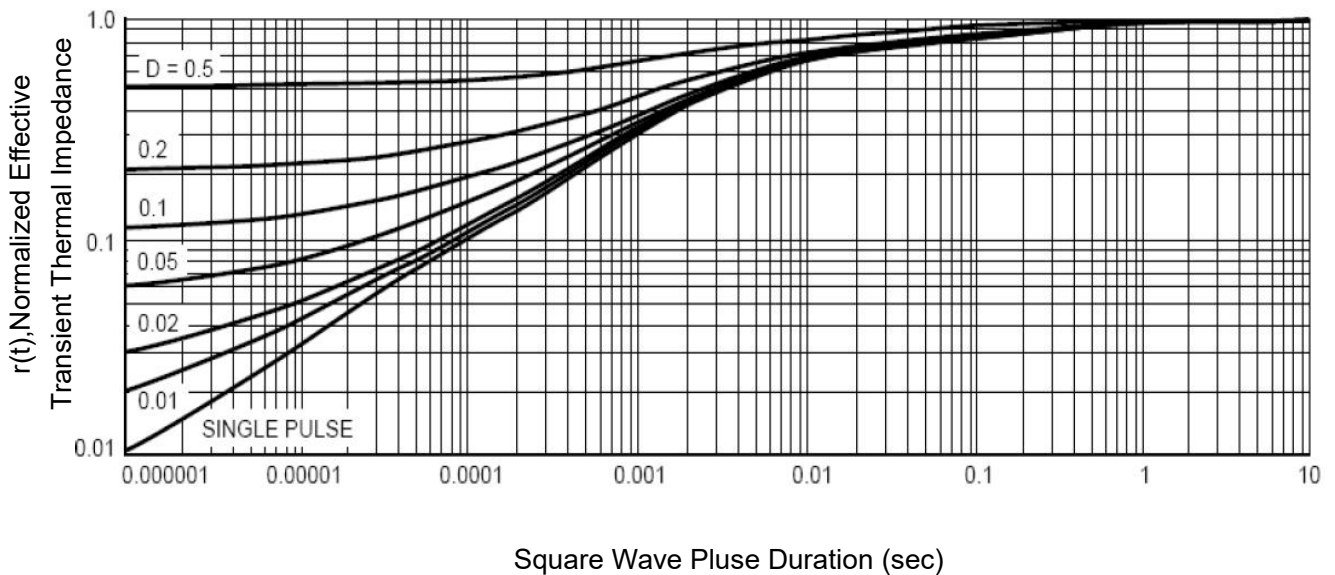
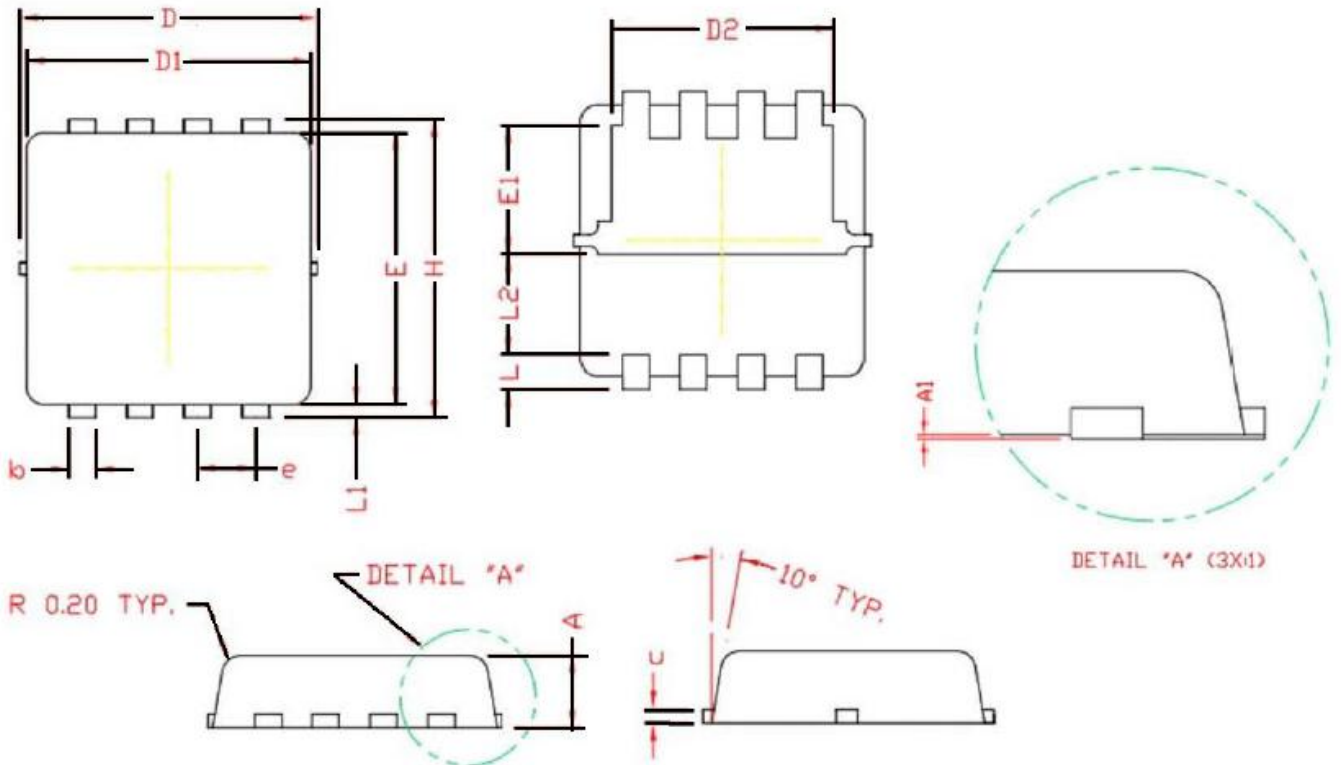


Figure 12 Normalized Maximum Transient Thermal Impedance

DFN3.3X3.3-8L Package Information



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

| SYMBOL | MIN       | NOM  | MAX  |
|--------|-----------|------|------|
| A      | 0.70      | 0.80 | 0.90 |
| A1     | 0.00      | 0.03 | 0.05 |
| b      | 0.24      | 0.30 | 0.35 |
| c      | 0.10      | 0.15 | 0.20 |
| D      | 3.25      | 3.32 | 3.40 |
| D1     | 3.05      | 3.15 | 3.25 |
| D2     | 2.40      | 2.50 | 2.60 |
| E      | 3.00      | 3.10 | 3.20 |
| E1     | 1.35      | 1.45 | 1.55 |
| e      | 0.65 BSC. |      |      |
| H      | 3.20      | 3.30 | 3.40 |
| L      | 0.30      | 0.40 | 0.50 |
| L1     | 0.10      | 0.15 | 0.20 |
| L2     | 1.13 REF. |      |      |

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